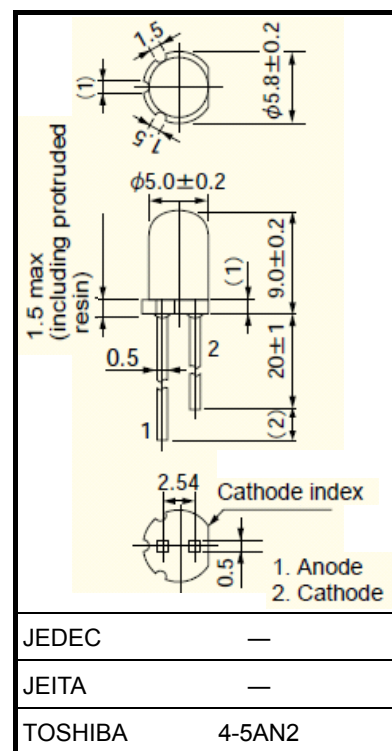


TLPGE18TP(F),TLFGE18TP(F),TLGE18TP(F),TLPYE18TP(F)

Panel Circuit Indicator

Unit: mm

- Lead(Pb)-free products (lead: Sn-Ag-Cu)
 - 5mm package
 - InGaAlP technology
 - All plastic mold type
 - Transparent lens
 - Lineup: 3 colors (pure green, green, pure yellow)
 - High intensity light emission
 - Excellent low current light output
 - Stopper lead type is also available
- TLPGE18T(F), TLFG18T(F), TLGE18T(F), TLPYE18T(F)
- Applications: outdoor message signboards, safety equipment, backlight, etc.



Weight: 0.31 g(Typ.)

Lineup

Product Name	Color	Material
TLPGE18TP(F)	Pure Green	InGaAsP
TLFGE18TP(F)	Green	
TLGE18TP(F)	Green	
TLPYE18TP(F)	Pure Yellow	

Absolute Maximum Ratings (Ta = 25°C)

Product Name	Forward Current I _F (mA)	Reverse Voltage V _R (V)	Power Dissipation P _D (mW)	Operating Temperature T _{opr} (°C)	Storage Temperature T _{stg} (°C)
TLPGE18TP(F)	50	4	120	-40~100	-40~120
TLFGE18TP(F)	50	4	120		
TLGE18TP(F)	50	4	120		
TLPYE18TP(F)	50	4	120		

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

TOSHIBA TLPGE18TP(F), TLFGE18TP(F), TLGE18TP(F), TLPYE18TP(F)

Electrical and Optical Characteristics (Ta = 25°C)

Product Name	Typ. Emission Wavelength				Luminous Intensity I _V			Forward Voltage V _F			Reverse Current I _R	
	λ _d	λ _p	Δλ	I _F	Min	Typ.	I _F	Typ.	Max	I _F	Max	V _R
TLPGE18TP(F)	558	(562)	14	20	85	200	20	2.1	2.4	20	50	4
TLFGE18TP(F)	565	(568)	15	20	85	300	20	2.0	2.4	20	50	4
TLGE18TP(F)	571	(574)	17	20	272	700	20	2.0	2.4	20	50	4
TLPYE18TP(F)	580	(583)	14	20	272	750	20	2.0	2.4	20	50	4
Unit	nm			mA	mcd		mA	V		mA	μA	V

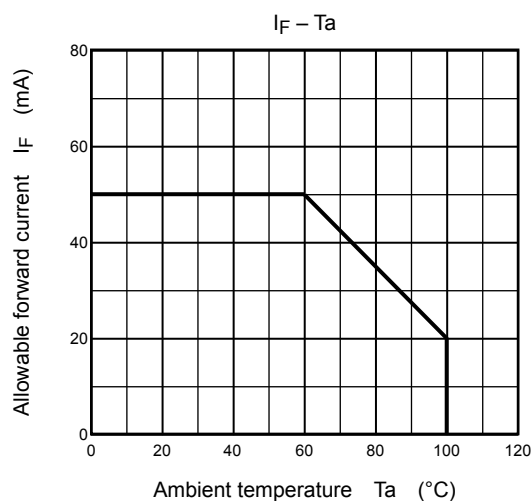
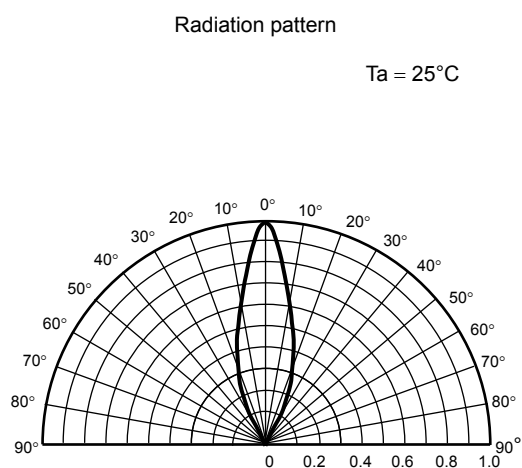
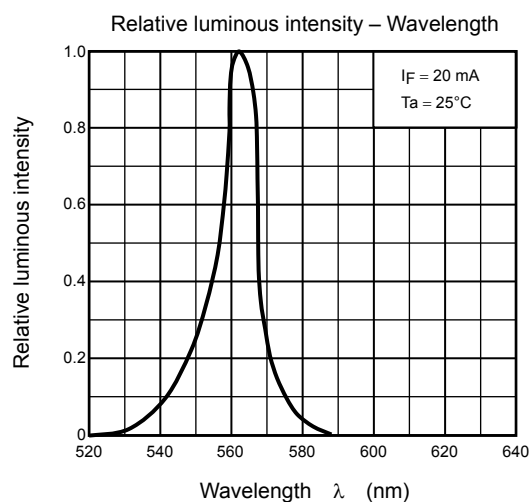
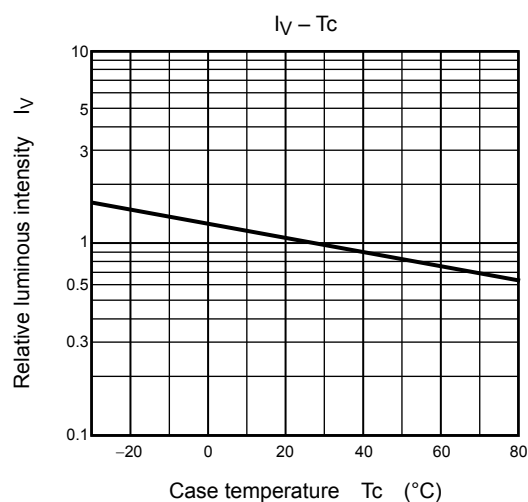
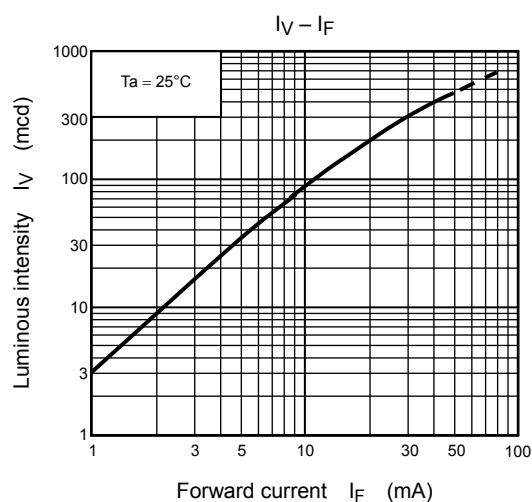
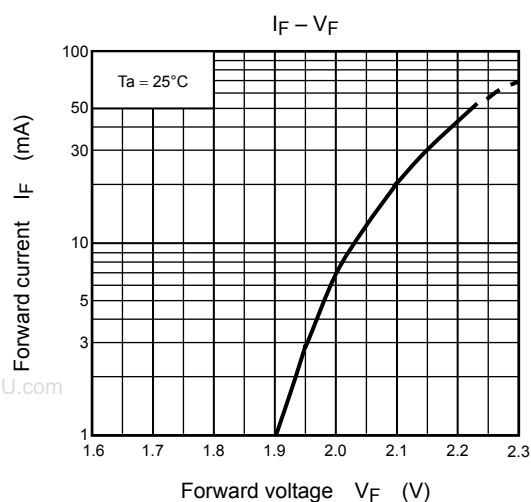
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Precautions

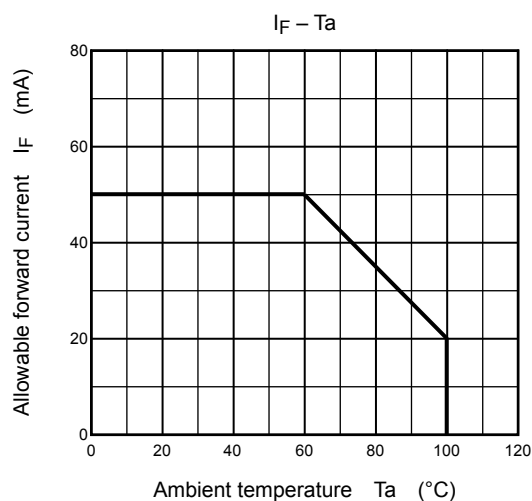
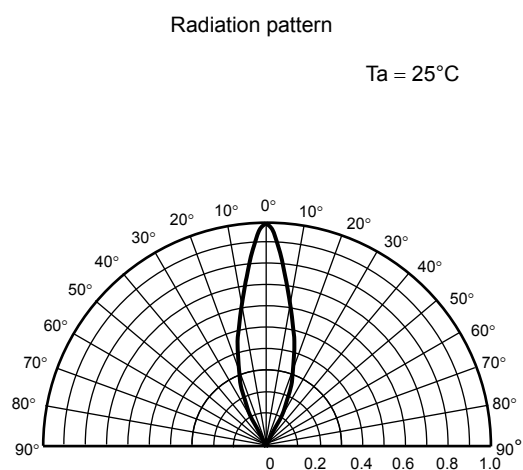
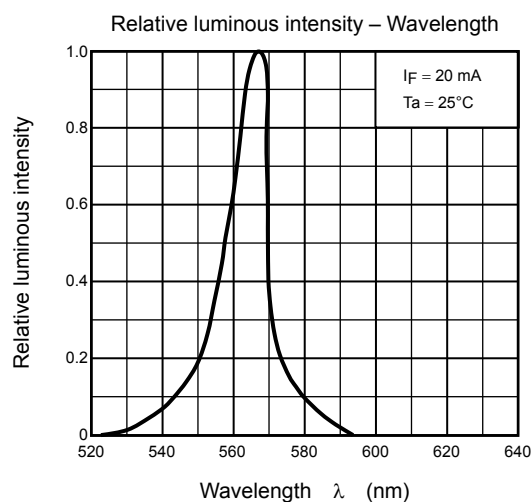
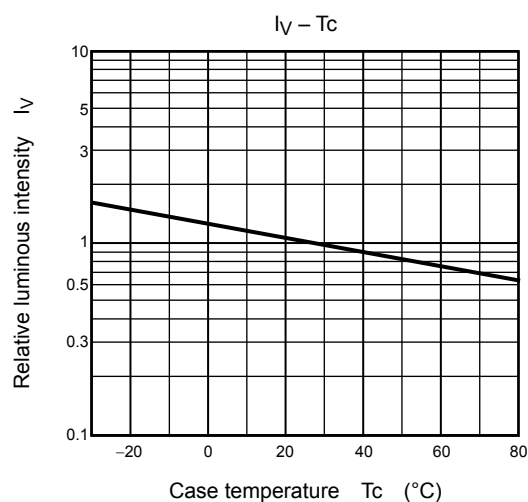
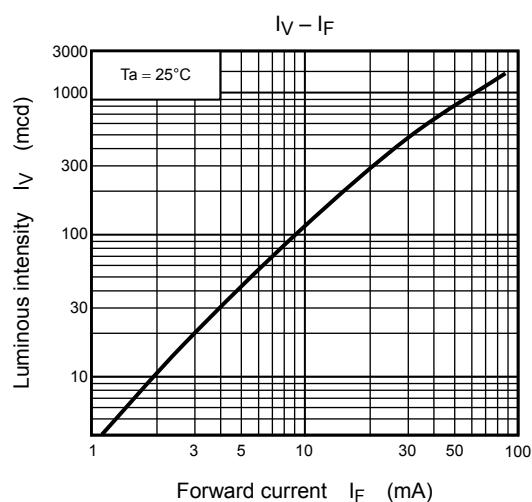
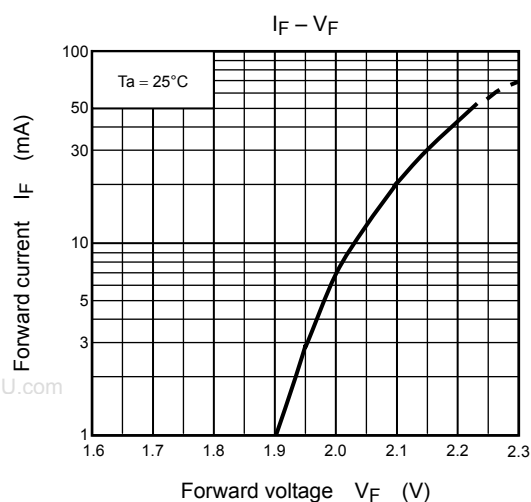
Please be careful of the following:

- Soldering temperature: 260°C max, soldering time: 3 s max
(soldering portion of lead: up to 1.6 mm from the body of the device)
- If the lead is formed, the lead should be formed up to 1.6 mm from the body of the device without forming stress to the resin. Soldering should be performed after lead forming.
- This visible LED lamp also emits some IR light.
If a photodetector is located near the LED lamp, please ensure that it will not be affected by this IR light.

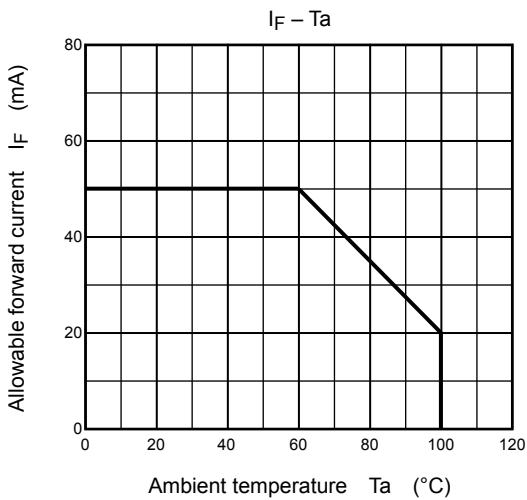
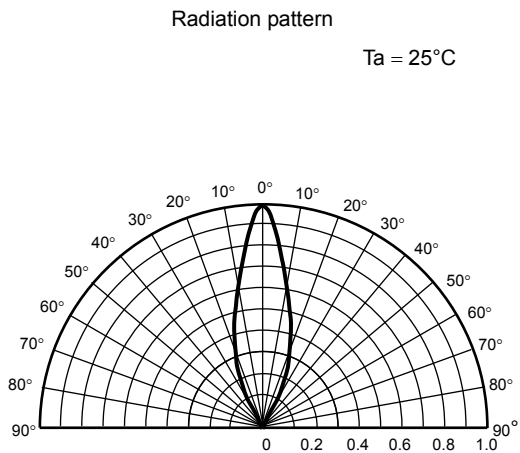
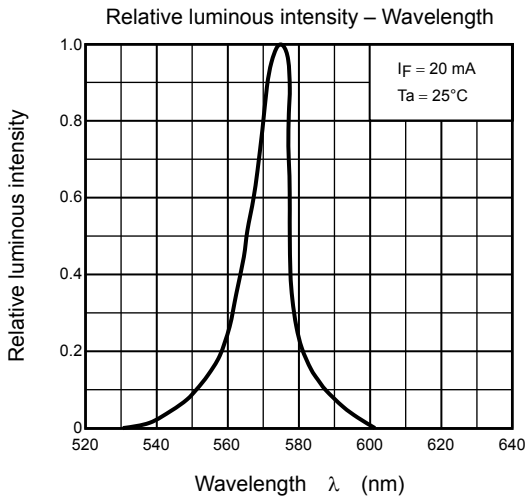
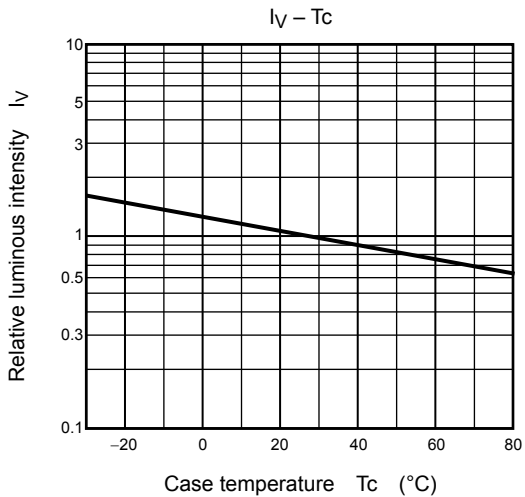
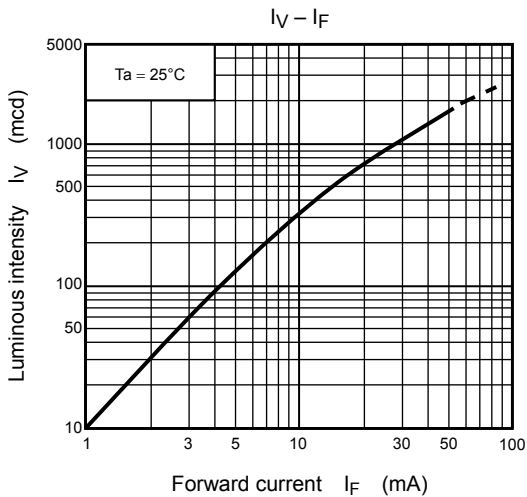
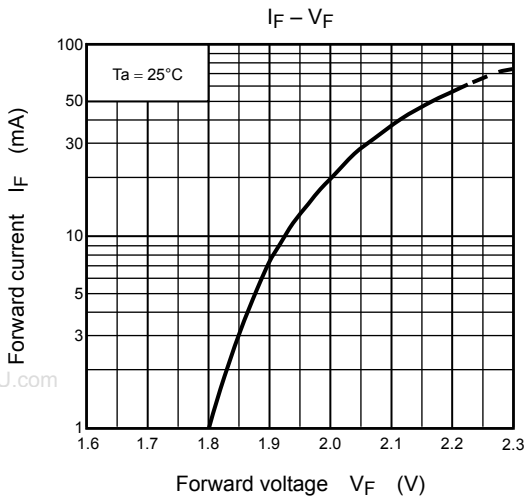
TLPGE18TP(F)



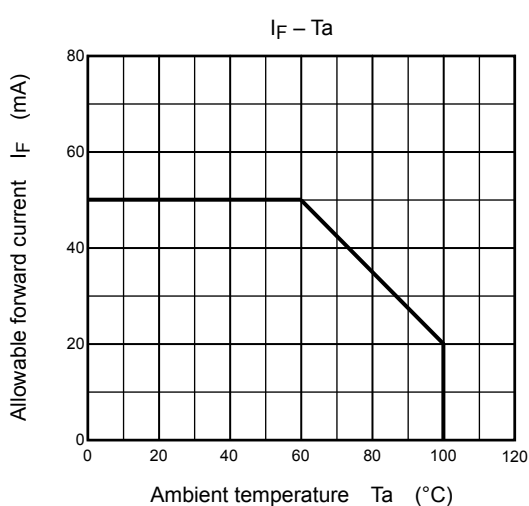
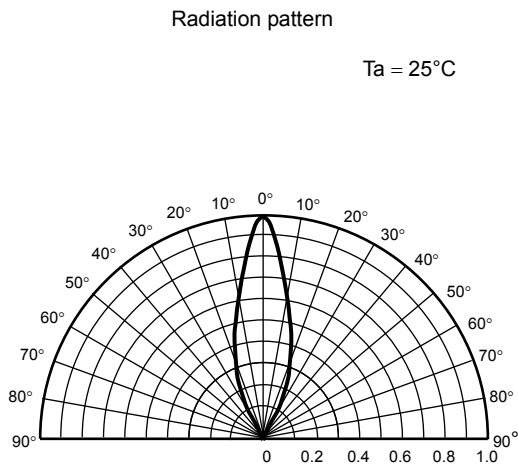
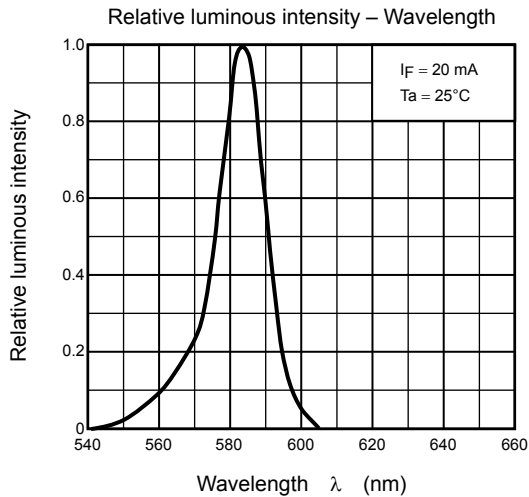
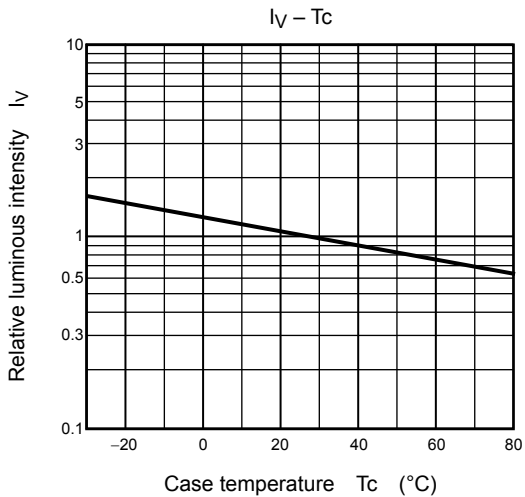
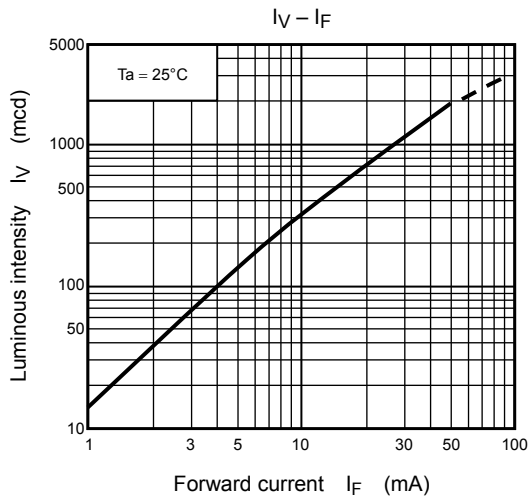
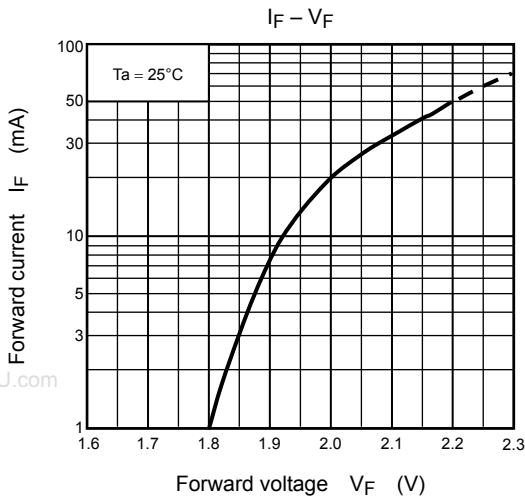
TLFGE18TP(F)



TLGE18TP(F)



TLPYE18TP(F)



RESTRICTIONS ON PRODUCT USE

20070701-EN

- The information contained herein is subject to change without notice.
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